

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5534488

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEXANDER TONKIKH	05/17/2019
PETER STAUSS	05/17/2019
RECEIVING PARTY DATA	
Name:	OSRAM OPTO SEMICONDUCTORS GMBH
Street Address:	LEIBNIZSTR. 4
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State/Country:	GERMANY
Postal Code:	93055
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16348662
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ATTORNEY DOCKET NUMBER:	EHF-19-1188
NAME OF SUBMITTER:	CAROL CONEY
SIGNATURE:	/cc/
DATE SIGNED:	05/22/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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EHF-19-1188

P2016,1347 US N (AAW/BLS) / 2016P01787WOUS

COMBINED DECLARATION/ASSIGNMENT

WHEREAS, we

Alexander Tonkikh of Wenzelbach, Germany
Peter Stauss of Regensburg, Germany

(hereinafter referred to as "the undersigned"), have made an invention entitled RADIATION-EMITTING SEMICONDUCTOR BODY AND METHOD OF PRODUCING A SEMICONDUCTOR LAYER SEQUENCE, identified in International Application No. PCT/EP2017/080035 and US Application No. 16/348,662,

the above-identified application was made or authorized to be made by the persons executing this Declaration;

we believe that we are the original joint inventors of a claimed invention in the application;

we hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, OSRAM Opto Semiconductors GmbH, with offices at Leibnizstr. 4, 93055 Regensburg, Germany (hereinafter referred to as "assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

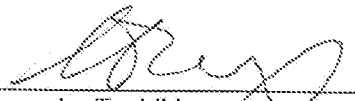
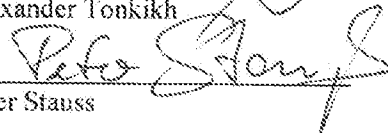
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The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the dates set forth below.

17.05.2019
Date

17.05.2019
Date


Alexander Tonkikh

Peter Stauss